

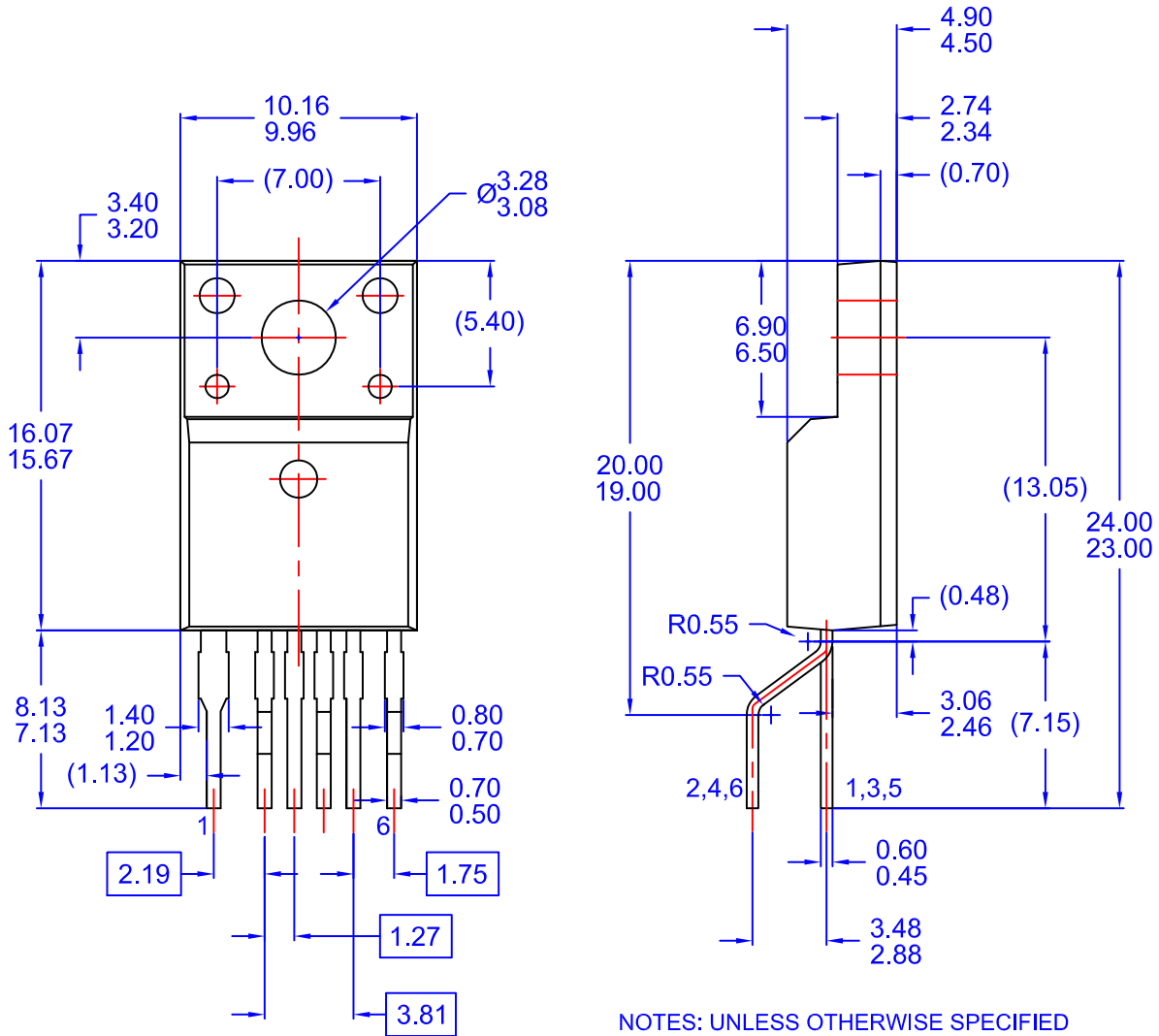
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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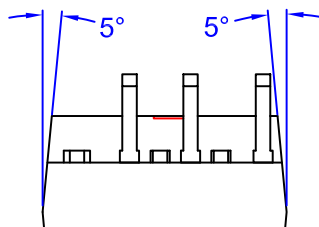


TO-220-6LD LF
CASE 340BG
ISSUE O

DATE 31 AUG 2016



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - D) LEADFORM OPTION A



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